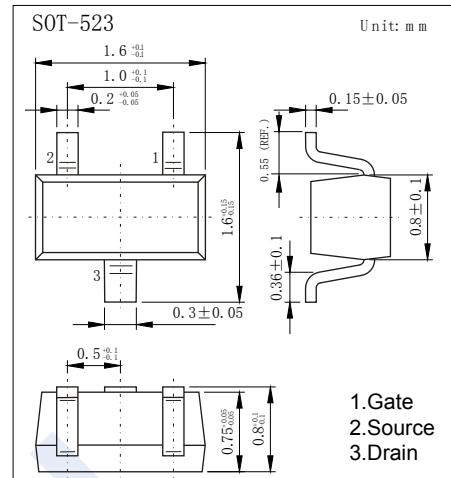
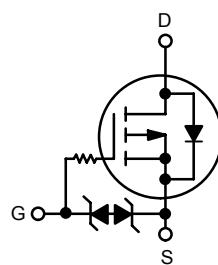


## P-Channel MOSFET

## NTA4151P

## ■ Features

- $V_{DS}$  (V) = -20V
- $I_D$  = -760mA ( $V_{GS}$  = -4.5V)
- $R_{DS(ON)}$  < 260m $\Omega$  ( $V_{GS}$  = -4.5V)
- $R_{DS(ON)}$  < 350m $\Omega$  ( $V_{GS}$  = -2.5V)
- $R_{DS(ON)}$  < 490m $\Omega$  ( $V_{GS}$  = -1.8V)

■ Absolute Maximum Ratings  $T_a$  = 25°C

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	$V_{DS}$	-20	V
Gate-Source Voltage	$V_{GS}$	±6	
Gate-to-Source ESD Rating – (Human Body Model, Method 3015)	ESD	1.8	kV
Continuous Drain Current	$I_D$	-0.76	A
Pulsed Drain Current @ $t_p$ = 10 us	$I_{DM}$	-1	
Power Dissipation	$P_D$	301	mW
Thermal Resistance.Junction- to-Ambient	$R_{thJA}$	415	°C/W
Lead Temperature for Soldering Purposes (1/8 in from case for 10 s)	$T_L$	260	°C
Junction Temperature	$T_J$	150	
Junction Storage Temperature Range	$T_{stg}$	-55 to 150	

## P-Channel MOSFET

## NTA4151P

■ Electrical Characteristics  $T_a = 25^\circ\text{C}$ 

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	$V_{DSS}$	$I_D = -250 \mu\text{A}, V_{GS} = 0\text{V}$	-20			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = -16\text{V}, V_{GS} = 0\text{V}$			-100	nA
Gate-Body leakage current	$I_{GSS}$	$V_{DS} = 0\text{V}, V_{GS} = \pm 4.5\text{V}$			$\pm 10$	uA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -250 \mu\text{A}$	-0.45		-1.2	V
Static Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS} = -4.5\text{V}, I_D = -350\text{mA}$ (Note.1)		260	360	$\text{m}\Omega$
		$V_{GS} = -2.5\text{V}, I_D = -300\text{mA}$ (Note.1)		350	450	
		$V_{GS} = -1.8\text{V}, I_D = -150\text{mA}$ (Note.1)		490	1000	
Forward Transconductance	$g_{FS}$	$V_{DS} = -10\text{V}, I_D = 250\text{mA}$ (Note.1)		0.4		S
Input Capacitance	$C_{iss}$	$V_{GS} = 0\text{V}, V_{DS} = -5\text{V}, f = 1\text{MHz}$		156		$\text{pF}$
Output Capacitance	$C_{oss}$			28		
Reverse Transfer Capacitance	$C_{rss}$			18		
Total Gate Charge	$Q_g$	$V_{GS} = -4.5\text{V}, V_{DS} = -10\text{V}, I_D = -0.3\text{A}$		2.1		$\text{nC}$
Threshold Gate Charge	$Q_{gth}$			0.125		
Gate Source Charge	$Q_{gs}$			0.325		
Gate Drain Charge	$Q_{gd}$			0.5		
Turn-On Delay Time	$t_{d(on)}$	$V_{GS} = -4.5\text{V}, V_{DS} = -10\text{V}, I_D = -200\text{mA}, R_G = 10\Omega$		8		$\text{ns}$
Turn-On Rise Time	$t_r$			8.2		
Turn-Off Delay Time	$t_{d(off)}$			29		
Turn-Off Fall Time	$t_f$			20.4		
Maximum Body-Diode Continuous Current	$I_S$				-250	mA
Diode Forward Voltage	$V_{SD}$	$I_S = 250\text{mA}, V_{GS} = 0\text{V}$			-1.1	V

Note.1: Pulse Test: pulse width  $\leq 300\text{us}$ , duty cycle  $\leq 2\%$ .

## ■ Marking

Marking	** M
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## P-Channel MOSFET

### NTA4151P

#### ■ Typical Characteristics

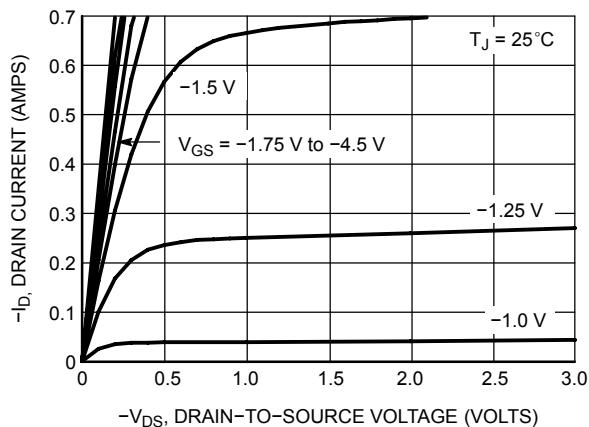


Figure 1. On-Region Characteristics

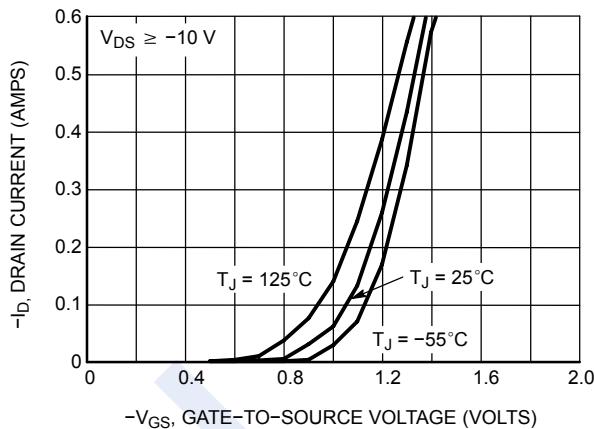


Figure 2. Transfer Characteristics

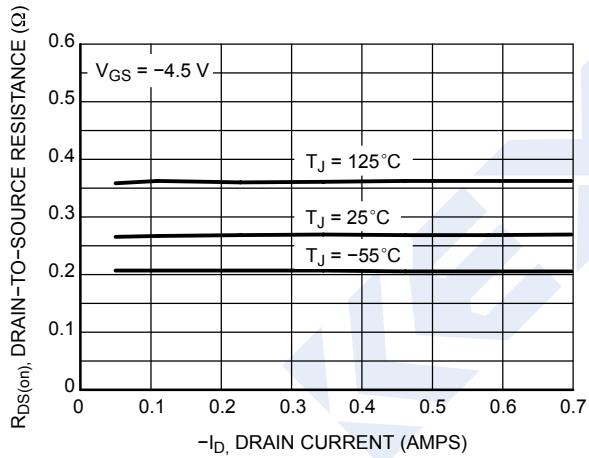


Figure 3. On-Resistance vs. Drain Current and Temperature

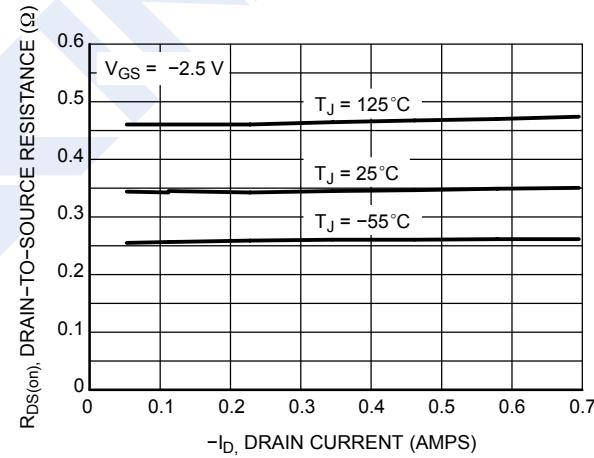


Figure 4. On-Resistance vs. Drain Current and Temperature

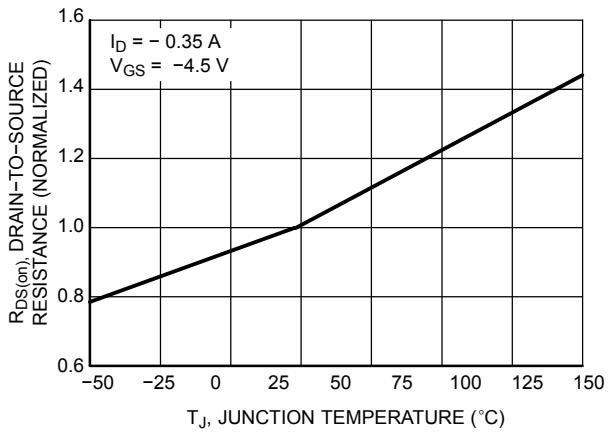


Figure 5. On-Resistance Variation with Temperature

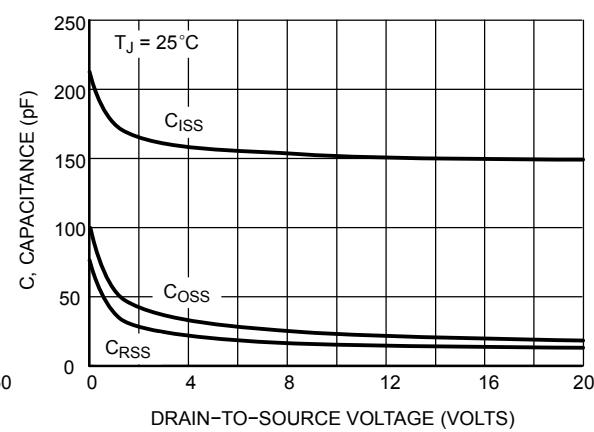


Figure 6. Capacitance Variation

## P-Channel MOSFET

### NTA4151P

#### ■ Typical Characteristics

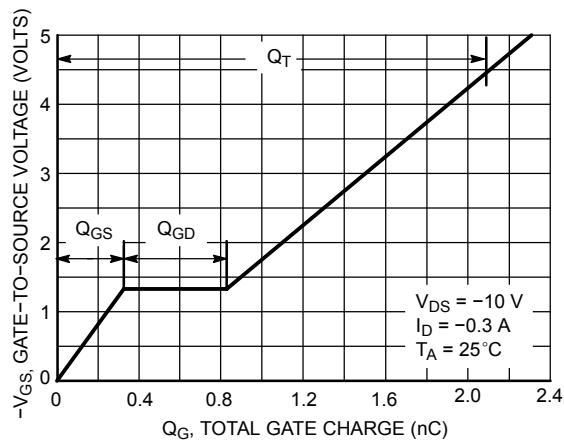


Figure 7. Gate-to-Source Voltage vs. Total Gate Charge

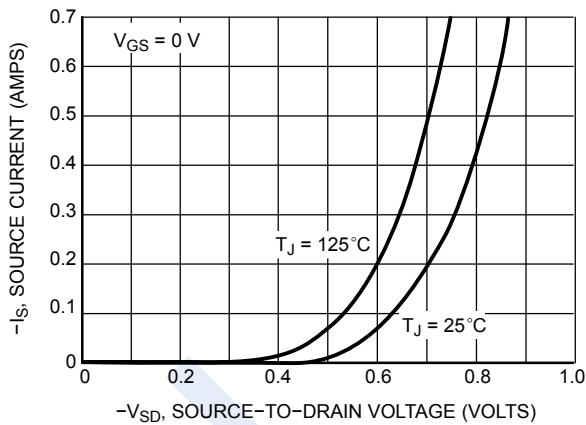


Figure 8. Diode Forward Voltage vs. Current

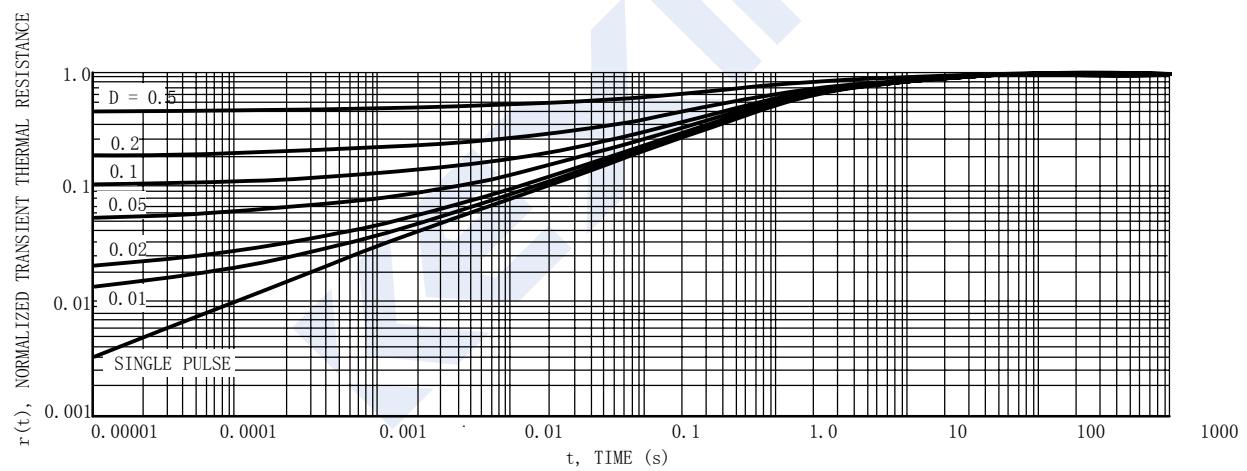


Figure 9. Normalized Thermal Response